

Title (en)
METHOD FOR ELECTRICALLY CONDUCTIVELY CONTACTING AN OPTOELECTRONIC COMPONENT HAVING AT LEAST ONE PROTECTIVE LAYER AND OPTOELECTRONIC COMPONENT HAVING A CONTACTING OF THIS TYPE

Title (de)
VERFAHREN ZUR ELEKTRISCH LEITENDEN KONTAKTIERUNG EINES MINDESTENS EINE SCHUTZSCHICHT AUFWEISENDEN OPTOELEKTRONISCHEN BAUELEMENTS UND OPTOELEKTRONISCHES BAUELEMENT MIT EINER SOLCHEN KONTAKTIERUNG

Title (fr)
PROCÉDÉ DE MISE EN CONTACT ÉLECTROCONDUCTRICE D'UN COMPOSANT OPTOÉLECTRONIQUE COMPORTANT AU MOINS UNE COUCHE DE PROTECTION ET COMPOSANT OPTOÉLECTRONIQUE MUNI D'UN TELLE MISE EN CONTACT

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Application
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Abstract (en)
[origin: WO2021032250A1] The invention relates to a method for electrically conductively contacting an optoelectronic component (10) having at least one protective layer (7), wherein a) the optoelectronic component (10) having the at least one protective layer (7) is provided, wherein the optoelectronic component (10) has at least one bus bar (1) arranged under the at least one protective layer (7), b) at least one opening (8) is formed in the at least one protective layer (7) by means of laser ablation using at least one laser beam, wherein the wavelength range of the laser is 8 pm to 12 pm, wherein at least one bus bar (1) arranged under the at least one protective layer (7) is at least partially exposed such that the at least one bus bar (1) is not damaged, c) a low-melting solder is introduced into the at least one opening (8) of the at least one protective layer (7), and a flexible electrically conductive element (2) is aligned and fixed on a side of the at least one opening (8) opposite the at least one bus bar (1); and d) by means of induction soldering with a uniform heat input, an electrically conductive connection element (11) is formed in the at least one opening (8) such that the electrically conductive element (2) and the at least one bus bar (1) are electrically conductively contacted via the at least one connection element (11).

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